



PROFIBUS DPV1 Master Communication Module MVI46-PDPMV1

With the growing usage of the PROFIBUS DPV1 protocol in the industrial marketplace, this product has a wide variety of application uses. Industries that use this technology include:

- Power and distribution applications
- Petrochemical
- Water and Gas Applications
- SCADA and DCS applications

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PROFIBUS DPV1 Master Communication Module

MVI46-PDPMV1

The PROFIBUS DPV1 Master module is a powerful communication interface for SLC processors. Developed under license from Rockwell Automation, the module incorporates proprietary backplane technology that enables powerful data exchange with SLC processors.

Features and Benefits

The module supports complete Master specifications according to IEC 61158. Acyclic parameter data can be transferred with Class 1 or Class 2 DPV1 services, allowing processors to easily communicate with slave devices supporting PROFIBUS DPV0/V1 protocol.

The module acts as an input/output module between the PROFIBUS network and the SLC processor. Data transfer from the processor is asynchronous with the I/O data transfer on the PROFIBUS network.

General Specifications

- Single Slot - 1746 backplane compatible (Local or extended I/O rack only. Remote rack not supported)
- The module is recognized as an Input/Output module and has access to processor memory for data transfer between processor and module using M0/M1 files
- Ladder Logic is used for data transfer between module and processor. Sample ladder file included

Specification	Description
Form Factor	Single Slot SLC chassis compatible
Backplane current load	800 mA @ 5 V
Operating Temperature	0 to 60°C (32 to 140°F)
Storage Temperature	-40 to 85°C (-40 to 185°F)
Shock	30g operational, 50g non-operational
Relative Humidity	5% to 95% (non-condensing)
Processor	Compatible with Rockwell Automation SLC 5/02 M0/M1 capable processors or newer
LED indicators	Module status, Backplane transfer status, Application status, Serial activity and error LED status

